

**PATENT ASSIGNMENT**

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Kwan-Sic Chun	07/02/2010
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Samsung SDI Co., Ltd.
<b>Street Address:</b>	428-5, Gongse-dong, Giheung-gu
<b>City:</b>	Yongin-si, Gyeonggi-do
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12844676
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(949)760-9502
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	9497600404
<b>Email:</b>	efiling@kmob.com
<b>Correspondent Name:</b>	Knobbe Martens Olson & Bear LLC
<b>Address Line 1:</b>	2040 Main Street
<b>Address Line 2:</b>	14th Floor
<b>Address Line 4:</b>	Irvine, CALIFORNIA 92501
<b>ATTORNEY DOCKET NUMBER:</b>	SDIYPL.248AUS
<b>NAME OF SUBMITTER:</b>	Soyoung Jung
<b>Total Attachments: 1</b> source=Assignment SDIYPL.248AUS#page1.tif	

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PATENT

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Filing Date: Herewith

Client Code: SDIYPL248AUS  
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ASSIGNMENT

WHEREAS, I, the undersigned, have invented certain new and useful improvements in a SAFETY ELEMENT ASSEMBLY, the specification of which was executed on even date herewith.

AND WHEREAS, Samsung SDI Co., Ltd., (hereinafter "ASSIGNEE"), with its principal place of business at 428-5, Gongse-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea, desires to acquire the entire right, title, and interest in and to the said improvements with respect to the United States of America, its territories and possessions.

NOW, THEREFORE, in light of good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventors, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Date: July 2, 2010

Signature: Kwan-Sic Chun

Name: Kwan-Sic Chun  
Address : c/o Samsung SDI Co., Ltd.

428-5, Gongse-dong, Giheung-gu, Yongin-si,  
Gyeonggi-do, Republic of Korea

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